

SOT1329-1

plastic thin fine-pitch ball grid array package; 100 balls

10 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA100
Package type industry code	TFBGA100
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-7-2012

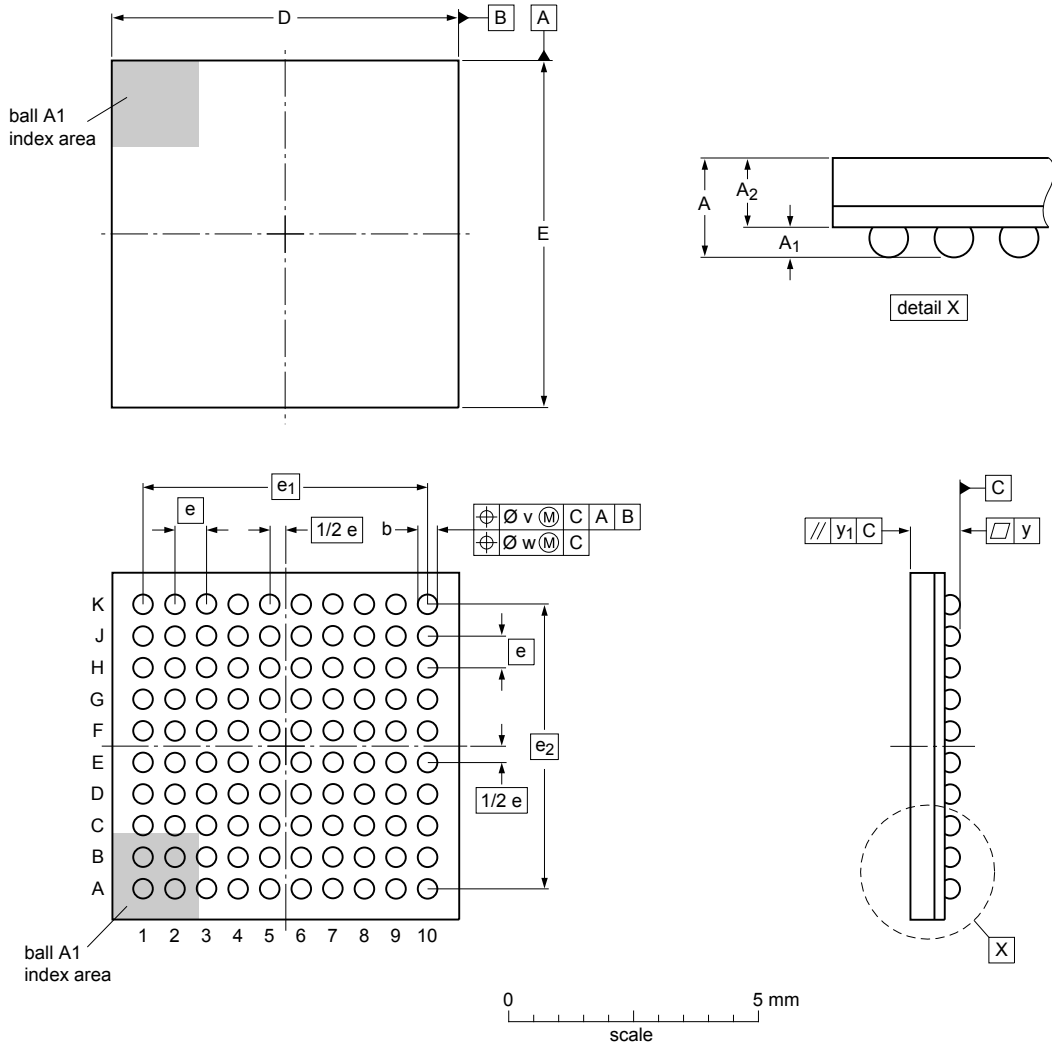
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.9	-	1	1.15	mm
A ₂	package height	0.65	-	0.7	0.8	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	100	-	



2. Package outline

TFBGA100: plastic thin fine-pitch ball grid array package; 100 balls SOT1329-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.15	0.35	0.80	0.45	7.1	7.1							
nom	1.00	0.30	0.70	0.40	7.0	7.0	0.65	5.85	5.85	0.15	0.05	0.08	0.1
min	0.90	0.25	0.65	0.35	6.9	6.9							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1329-1					12-05-07- 12-06-14

Fig. 1. Package outline TFBGA100 (SOT1329-1)

3. Legal information

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Date of release: 10 February 2016
